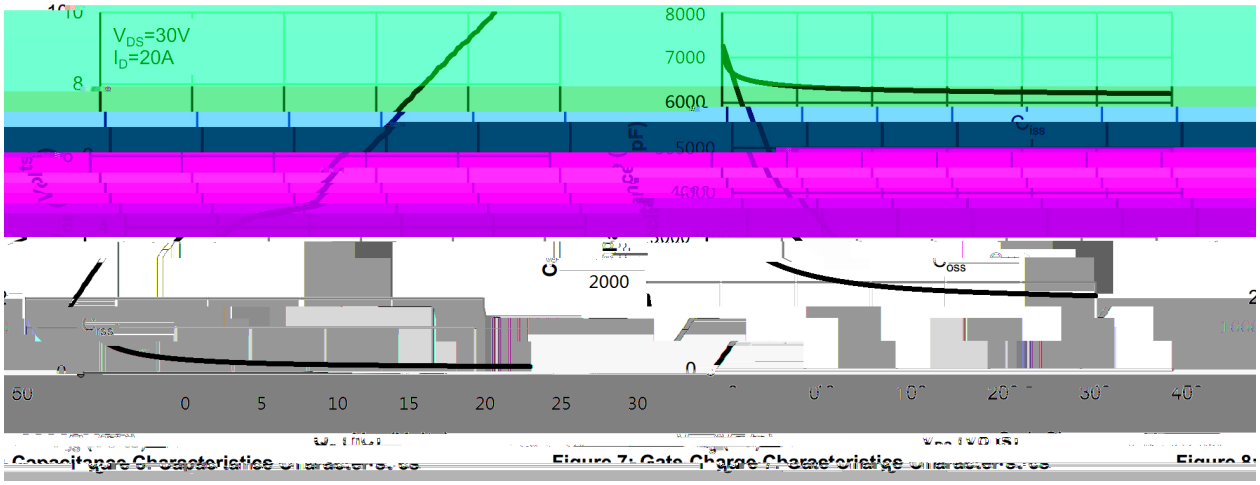
TO-263

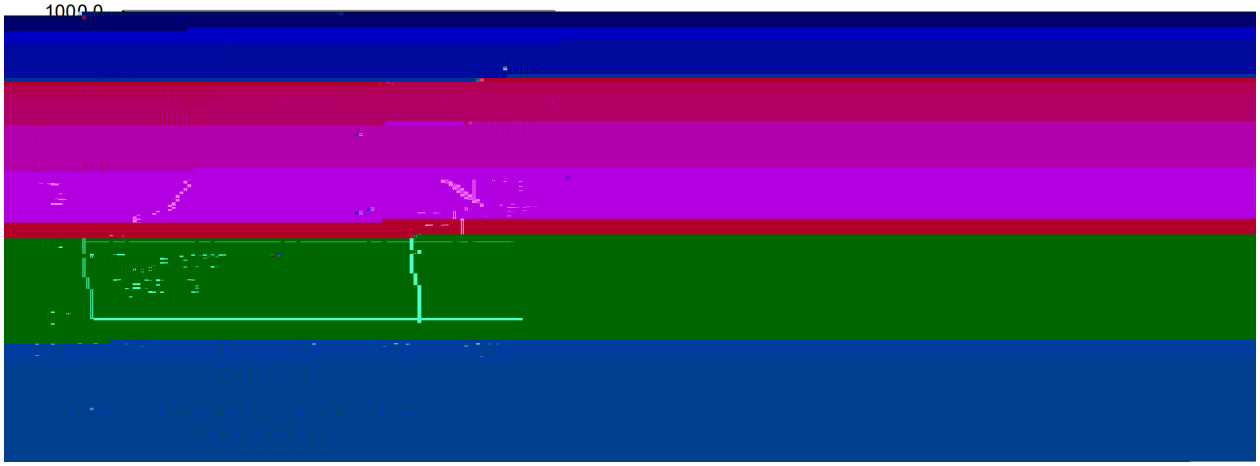
@ *f* Parameter	… Z Symbol	*f* › Rating	% y Unit
Drain-Source Voltage	V_{DSS}	60	V
Drain Current	I_D(Tc=25)	182	A
Pulsed Drain Current	I_{DM}	530	A
Gate-Source Voltage	V_{GS}	f 20	V
Single Pulsed Avalanche Energy(L=0.5mH)	E_{AS}	946	mJ
Avalanche Current	I_{AS}	43.5	A
Total Power Dissipation	P_D(Tc=25)	180	W
Junction and Storage Temperature Range	T_J,T_{STG}	-55 to 150	
Thermal Resistance-Junction to Ambient t 0 10s	R AS		

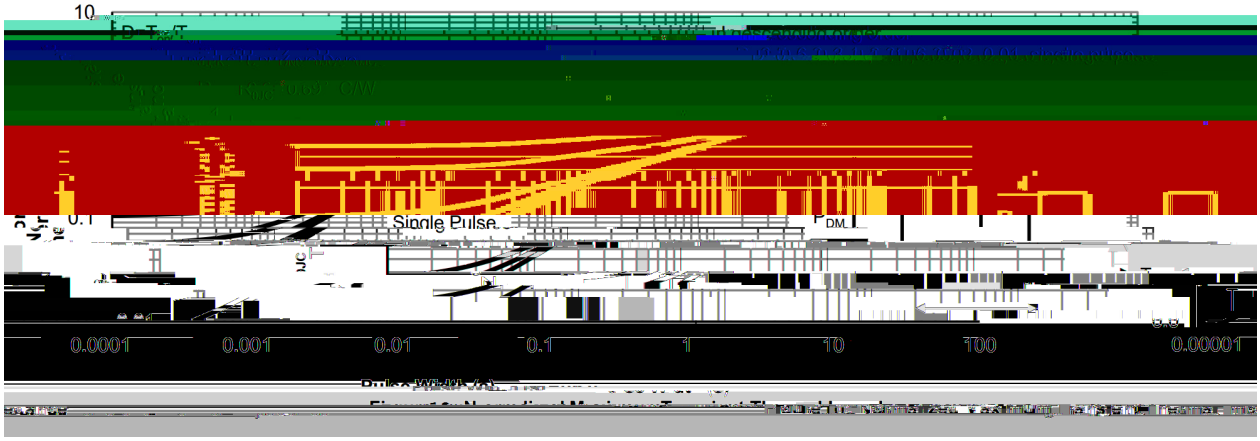
@ *f* Parameter	… Z Symbol	y ¡ Ú ^ Test Conditions	Â 4 › Min	Á º › Typ	Â Ý › Max	% y Unit
Turn-On Delay Time	$t_{d(on)}$			15.7		
Turn-On Rise Time	t_r	V_{GS}=10V V_{DS}=30V R_L=1.5 R_{GEN}=3		16.4		ns
Turn-Off Delay Time	t					

Ô ? d • Ž ¢ / Electrical Characteristic Curve

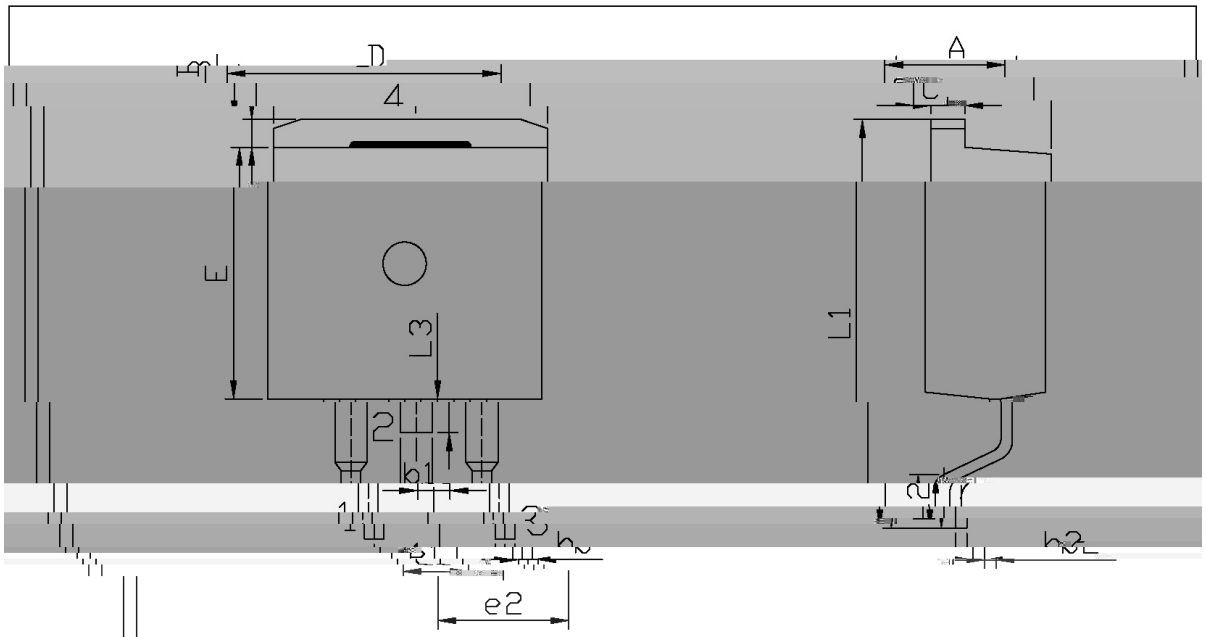


Capacitance Characteristics Figure 7: Gate Charge Characteristics Figure 8:





Ø ¤ =) ¢ / Package Dimensions



单位：mm

Dimensions In Millimeters		Dimensions In Millimeters			
Symbol	Min	Max	Symbol	Min	Max
A	4.30	4.70	E	9.00	9.40
b	1.00	1.40	e1	2.34	2.74

š WD t … • Ž ¢ (x /) / : K S V K X G Z [X K 6 X U L O R K L U X / 8 8 K L R U] 9 U R J K X O T M 6

ª ¢ y

1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;

2o• Q › “ † 245 r5 - k ž • 4 Ò 5 r0.5sec;

3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 - ž • y 10 r1 sec. Temp.:260±5 Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ˜ E	Units ;>û ¦H	Dimension ;>û p . (unit Æmm³)